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Colin Hinson

In the village of Blunham, Bedfordshire.



# XDS Memory Expansion

**XDS** Extended Development Support  
Installation and Operation Guide



TEXAS  
INSTRUMENTS



## PREFACE

The purpose of this manual is to familiarize the user with the functions and theory of the Memory Expansion board. The Memory Expansion Board is an optional circuit card for the XDS that greatly increases the capabilities of the system. This manual also describes installation instructions for the Memory Expansion board, part number 2311050-0001. The user and installer should read this manual before attempting to operate or install the Memory Expansion board. If the Memory Expansion board is removed from the XDS, this manual should be kept with the board for reference during future installation.

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## SECTION 1

### INSTALLATION

#### 1.1 INTRODUCTION

The Memory Expansion board is an option that significantly increases the emulating power of the XDS; (Extended Development Support System). Since not all emulators contain their full range of memory on the emulator board, this board allows memory to be expanded. This allows you to use known memory (in the emulator) that is completely under control of the emulator. The Memory Expansion board contains 128K Bytes (8 bits) of memory. Information on the use of the Memory Expansion board can be found in the emulator user's guide. The Memory Expansion board also contains the communications hardware for the XDS. Information on setting up the communications section of the board can be found in the XDS installation and operation guide. Note that this board is not an option for the XDS Model 11. This section should be referenced if the Memory Expansion board is not installed or it is to be moved.

##### 1.1.1 Board Preparation and Installation.

The Memory Expansion board does not require any special preparation for use. The communications section of the board requires switches to be set and a jumper plug to be installed. This information is can be referenced in the appropriate XDS Installation and Operation Guide.

##### 1.1.1.1 Board Configuration.

The Memory Expansion board is available in two configurations. The second configuration is called the communications board and is designed for emulators that do not require memory expansion. The communications board (PN 2311050-0002) contains no memory. Table 1-1 describes which configuration is used with each emulator system. The part number of the Memory Expansion board determines how the board is configured and which emulators it will support. This board is not field convertible from one configuraton to another. The communicaiton board may be used with emulators that use the memroy expansion option with the loss of the memory expansion

features. Figure 1-1 shows the memory expansion board and the switches and jumper for the communications section.

Table 1-1 Memory Expansion Board Configurations

Part Number	Emulator Type
2311050-0001	TMS99000
2311050-0001	TMS9995
2311050-0002	TMS32010
2311050-0002	TMS7000

### 1.1.2 Board Installation.

#### CAUTION

BEFORE INSTALLING OR REMOVING ANY BOARD, TURN OFF THE POWER TO THE XDS UNIT.

The XDS Model XX Installation and Operation Guide describes the procedure for installing or removing boards from the XDS unit. Refer to the manual appropriate for the XDS Model you are using. If a memory expansion/comm board is currently installed in the XDS it must be removed before another one can be installed. Only one memory expansion/comm board can be installed at any one time for the XDS to function properly. The memory expansion/comm board must be installed in slot number 4. The memory expansion or communications board is not an available option with the XDS Model 11.

Boards removed from the chassis should be stored so that they are protected from static discharge. Erase the board information on the chassis configuration label for each circuit board removed.

For the Memory Expansion board enter the following information on the chassis configuration label for slot number 4 as given in Table 1-2.

Figure 1-1 Memory Expansion Board PN 2311050

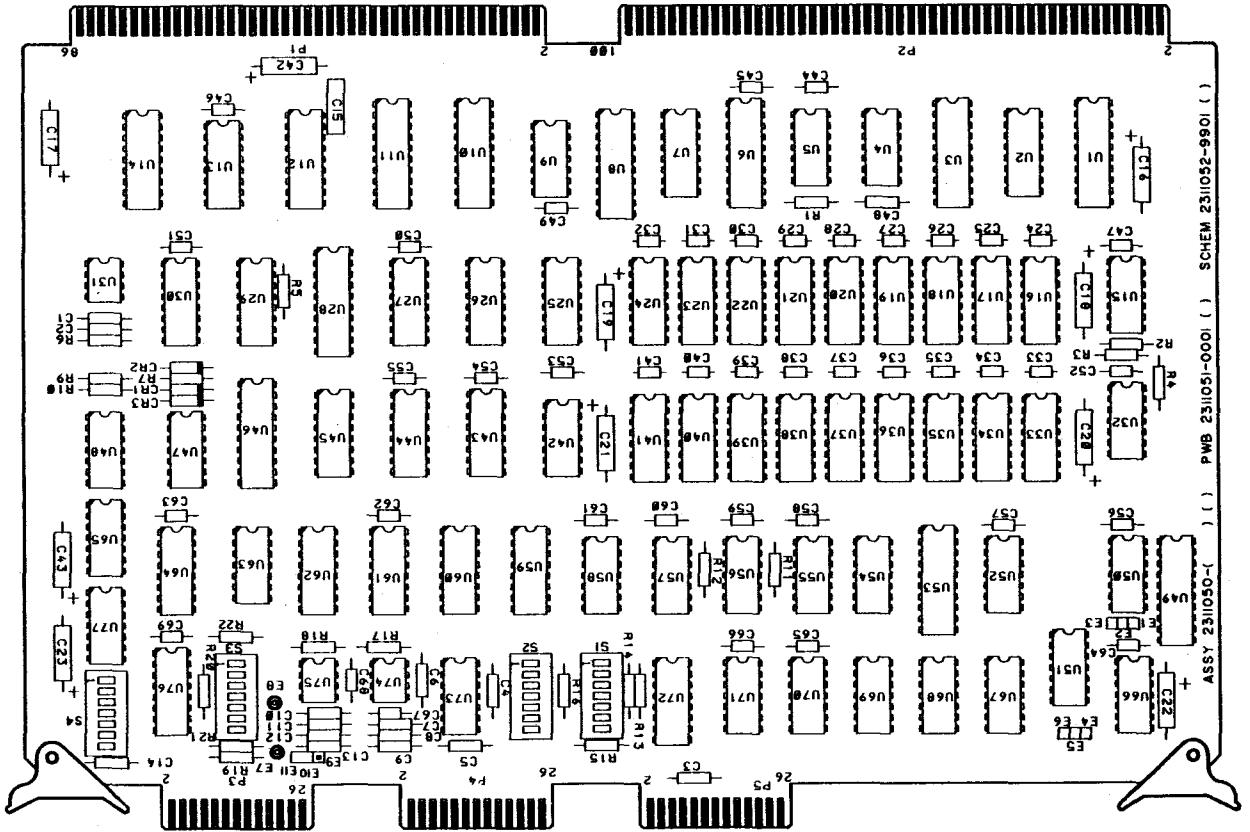




Table 1-2 Chassis Configuration Label Information

Block Title	Information to be Entered
PWB Description	MEMORY EXPANSION or COMMUNICATIONS
Part No	2311050-0001 OR 2311050-0002
REV	ENTER REVISION LETTER FROM MEMORY EXPANSION OR COMM BOARD.

#### 1.1.2.1 Installation Completion.

Complete the installation according to the information in the appropriate XDS installation and operation Guide. Note that cabling is required to the board in the chassis.

#### CAUTION

DO NOT OPERATE THE XDS UNIT WITH THE FRONT PANEL REMOVED. THE FRONT PANEL IS REQUIRED FOR PROPER AIR CIRCULATION AND COOLING OF THE CIRCUIT BOARDS. THE FRONT PANEL IS ALSO REQUIRED TO PREVENT LEAKAGE OF RFI/EMI RADIATION.

Restore power to the XDS unit. Refer to the appropriate emulator user's guide for further instructions on operating the XDS.

## SECTION 2

### HARDWARE FEATURES

#### 2.1 INTRODUCTION

The memory expansion board operates primarily with the emulator software that is referenced in the appropriate emulator user's guide. Also the features and applications of expansion memory are discussed in the emulators user's guide. The communications section is discussed in the XDS Installation and Operation Guide. The power requirements are discussed below.

##### 2.1.1 Power Requirements.

The DC power requirements for the Memory Expansion board are given in Table 2-1. This information may be used to calculate the total DC power requirements of the XDS system. When adding new boards to the system this DC Power calculation should be made to ensure that the XDS power supply will not be overloaded. Refer to the XDS Installation and Operation Manual for the power supply rating information, and the power requirements for the other circuit boards may be obtained from their appropriate reference manuals. The DC power available to the user from the XDS chassis takes into account that there will always be a communications board present; therefore only the power required for the memory expansion part of the board is needed for total DC power calculations.

Table 2-1 Memory Expansion DC Power Requirements

+ 5 VOLTS (AMPS)	+ 12 VOLTS (AMPS)	- 12 VOLTS (AMPS)
1.00	.2	.1

## 2.2 Block Diagram

Figure 2-1 shows a block diagram of the memory expansion board. The major blocks are the DRAM memory bank and the memory and address controllers.

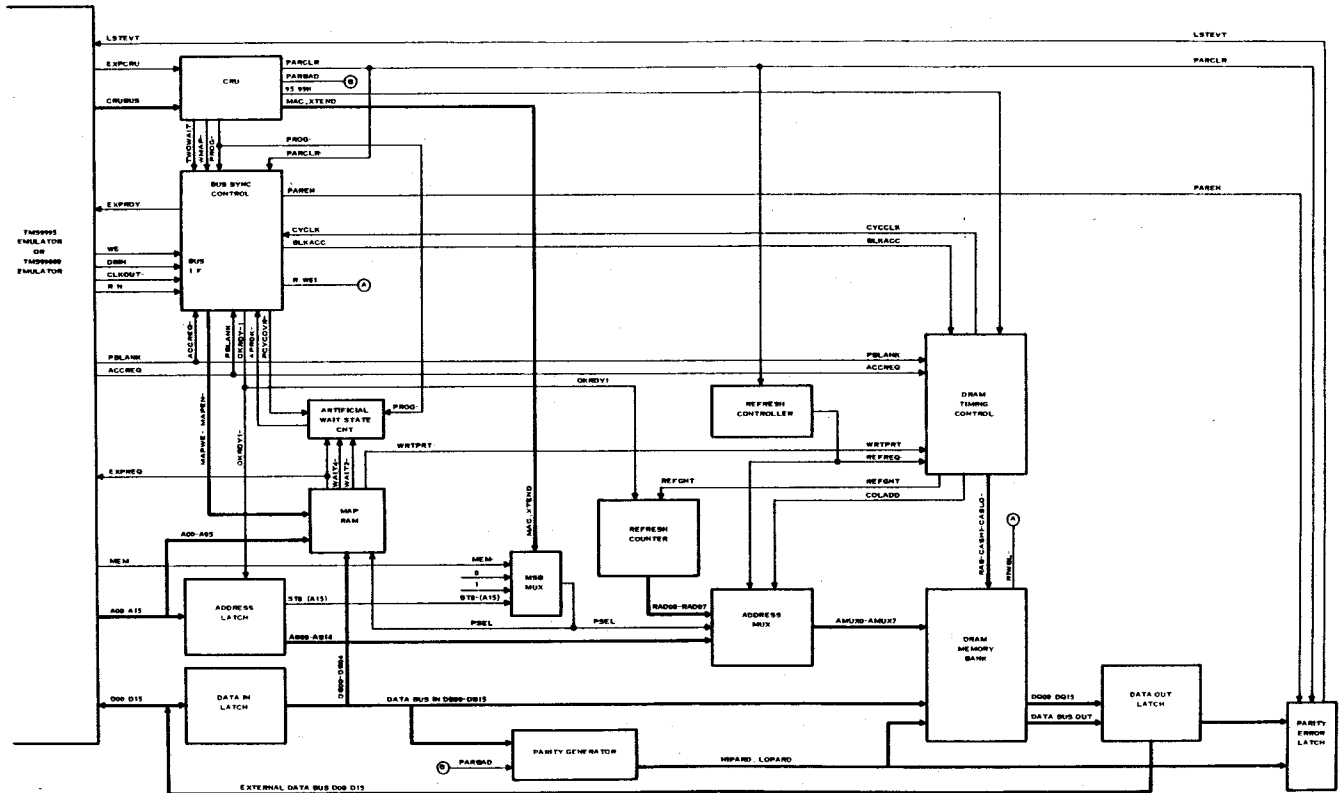



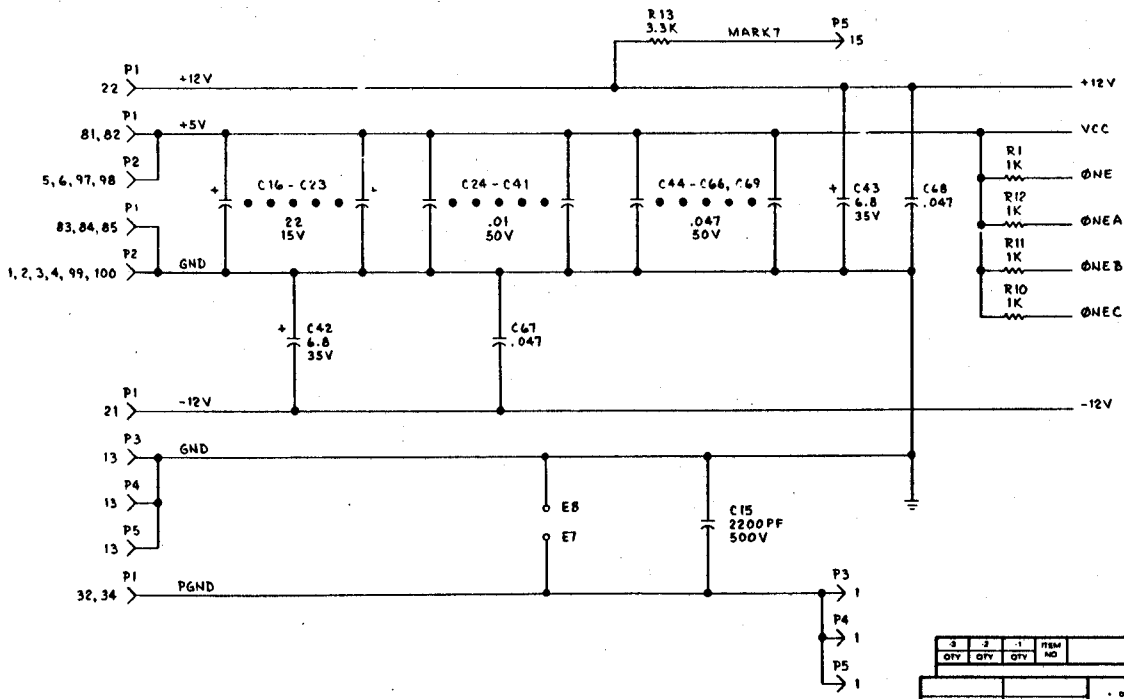
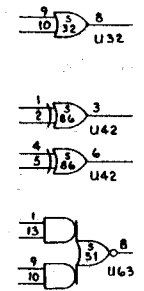
Figure 2-1 Memory Expansion Board Block Diagram

APPENDIX A

Memory Expansion Board Schematics

- NOTES UNLESS OTHERWISE SPECIFIED:
1. ALL DEVICE TYPES ARE PREFIXED WITH SN74.
  2. VCC IS APPLIED TO PIN 8 OF ALL 8-PIN IC'S, PIN 14 OF ALL 14-PIN IC'S, PIN 16 OF ALL 16-PIN IC'S, PIN 20 OF ALL 20-PIN IC'S, ETC.
  3. GROUND IS APPLIED TO PIN 4 OF ALL 8-PIN IC'S, PIN 7 OF ALL 14-PIN IC'S, PIN 6 OF ALL 16-PIN IC'S, PIN 10 OF ALL 20-PIN IC'S, ETC.
  4. DEVICE TYPE, PIN NUMBERS, AND REFERENCE DESIGNATOR OF IC IS SHOWN AS FOLLOWS:
- 
- LS00 AND LS04 = DEVICE TYPE  
 1, 2, AND 3 = PIN NUMBERS  
 U2 AND U14 = REFERENCE DESIGNATOR
5. RESISTANCE VALUES ARE IN OHMS.
  6. RESISTORS ARE 1/4 WATT, 5%.
  7. CAPACITANCE VALUES ARE IN MICROFARADS.
  8. MSB/LSB DEFINITIONS:  
 A00 = MSB      D00 = MSB  
 A15 = LSB      D15 = LSB

SAPRES

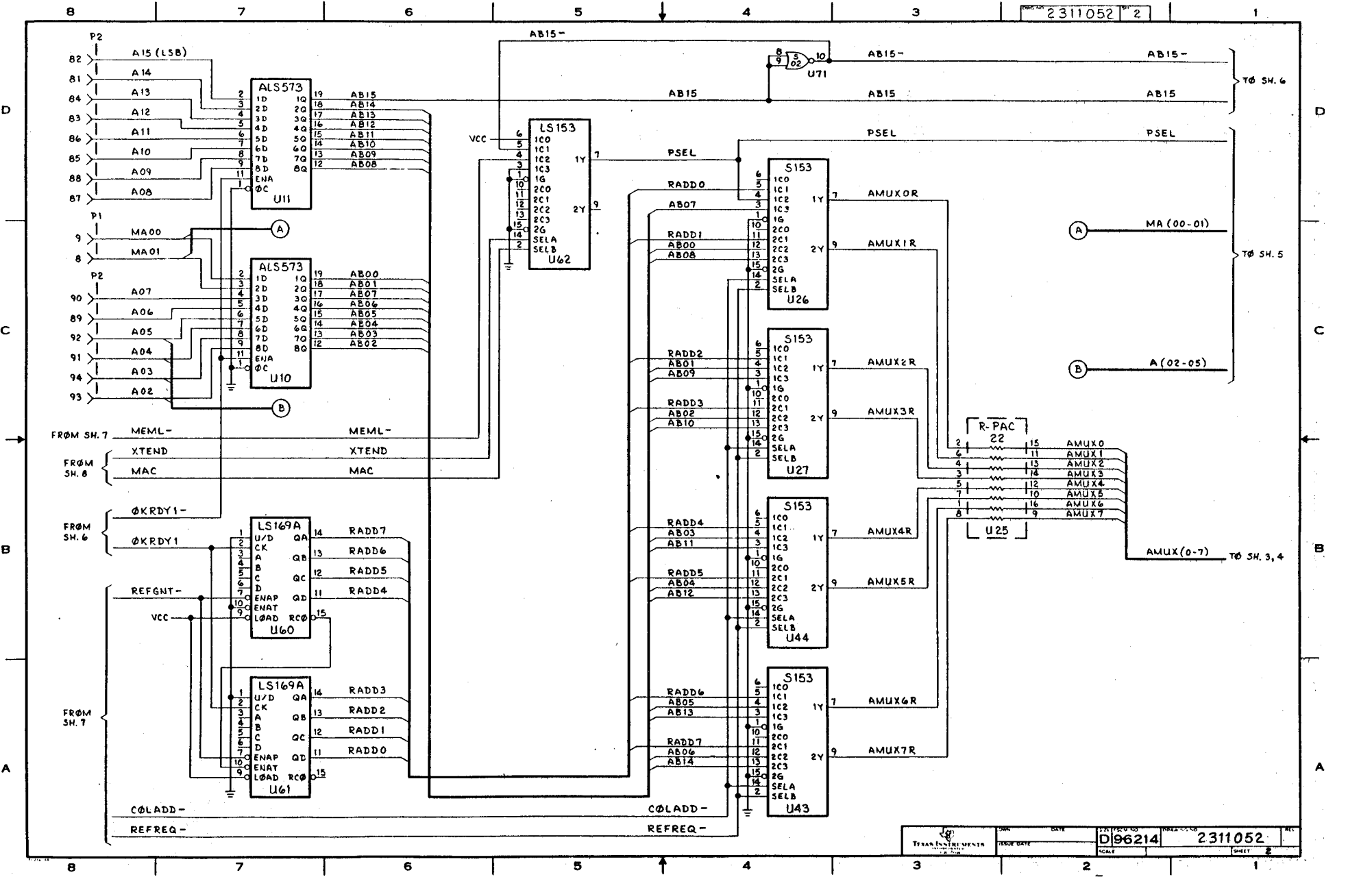


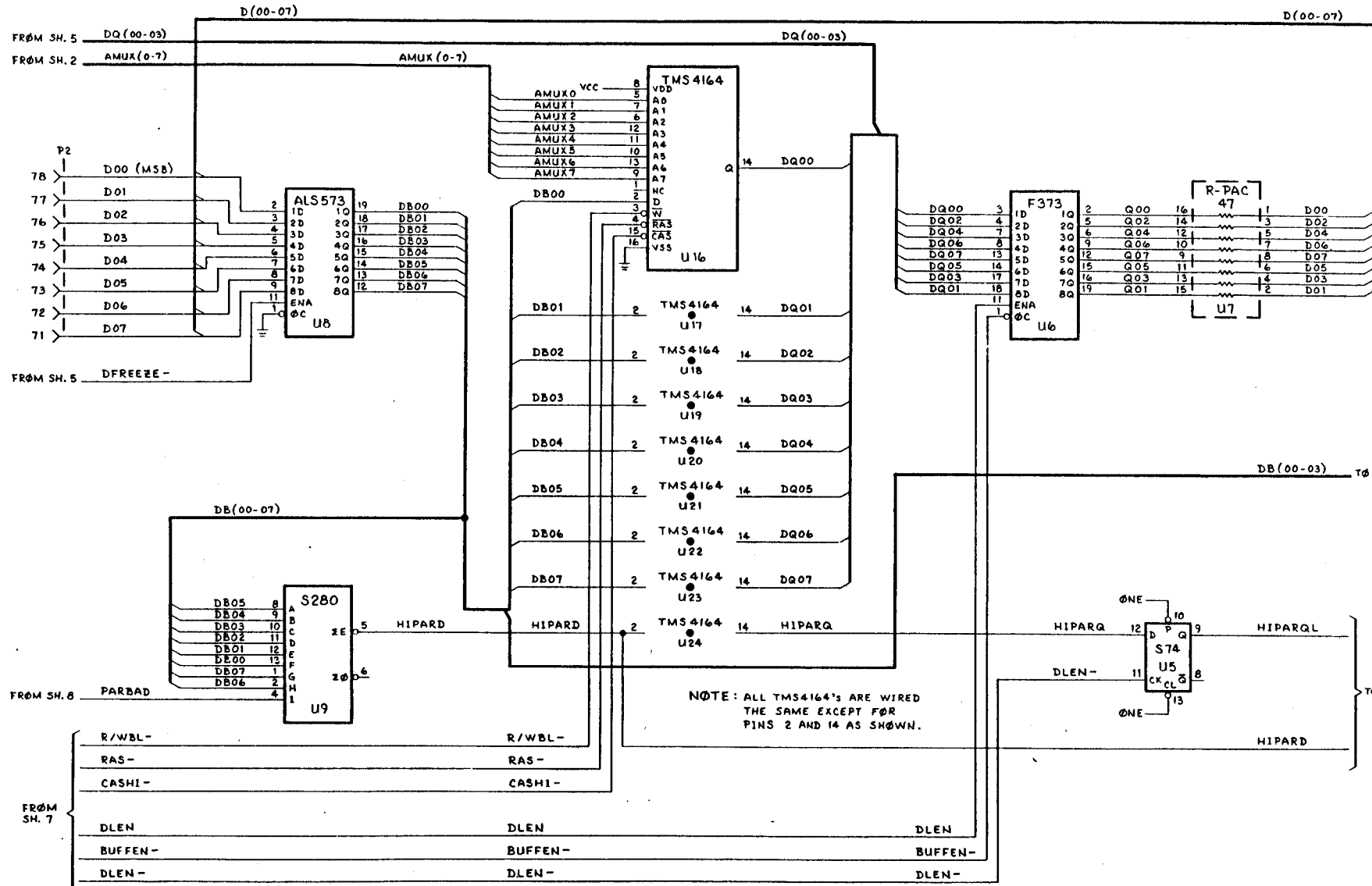
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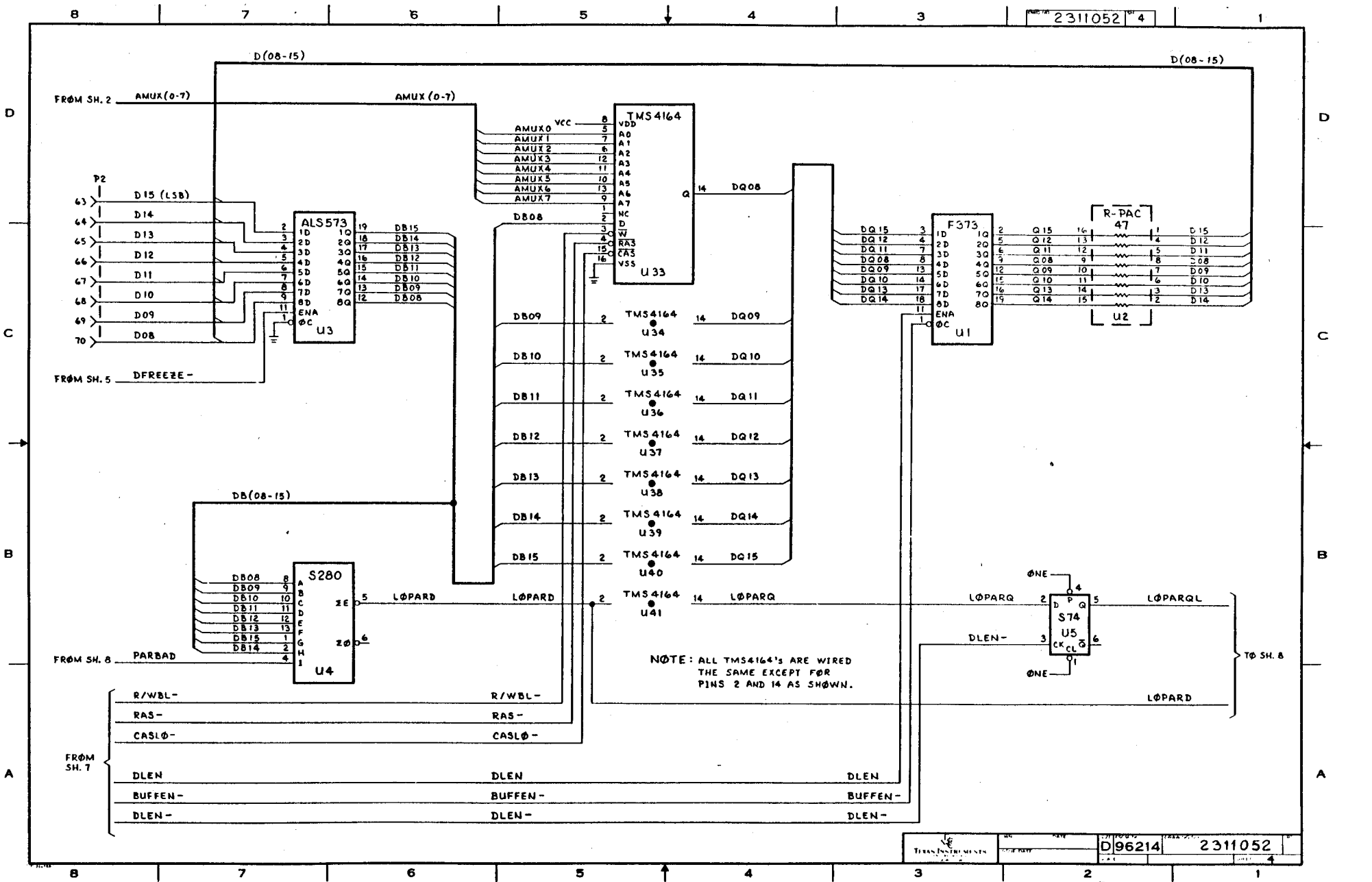
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2311050 7119 NEXT REV. USED ON: _____ APPLICATION: _____				D06668 2311052 SCALE: 1:21:1		SHEET 1 OF 15



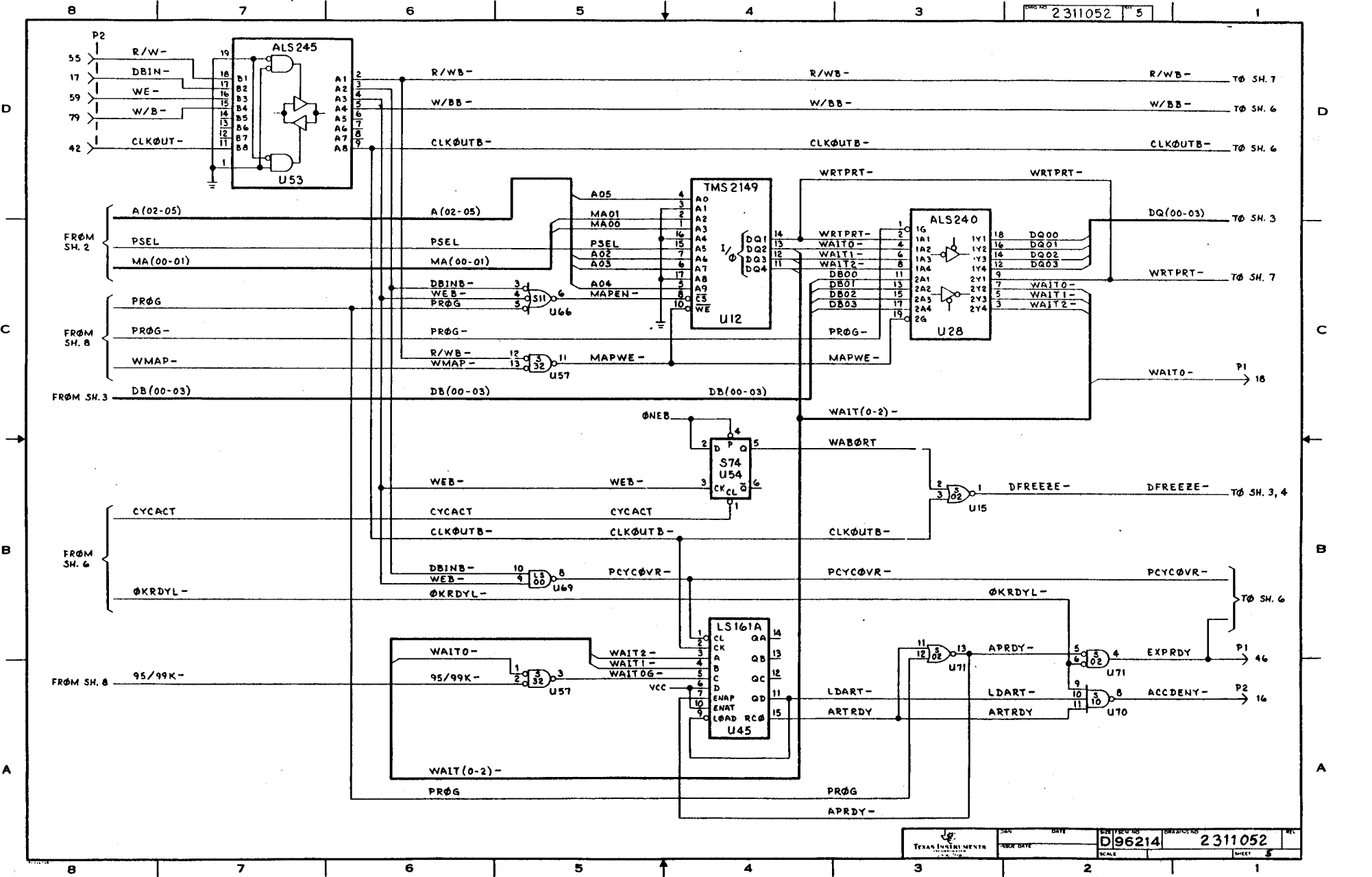


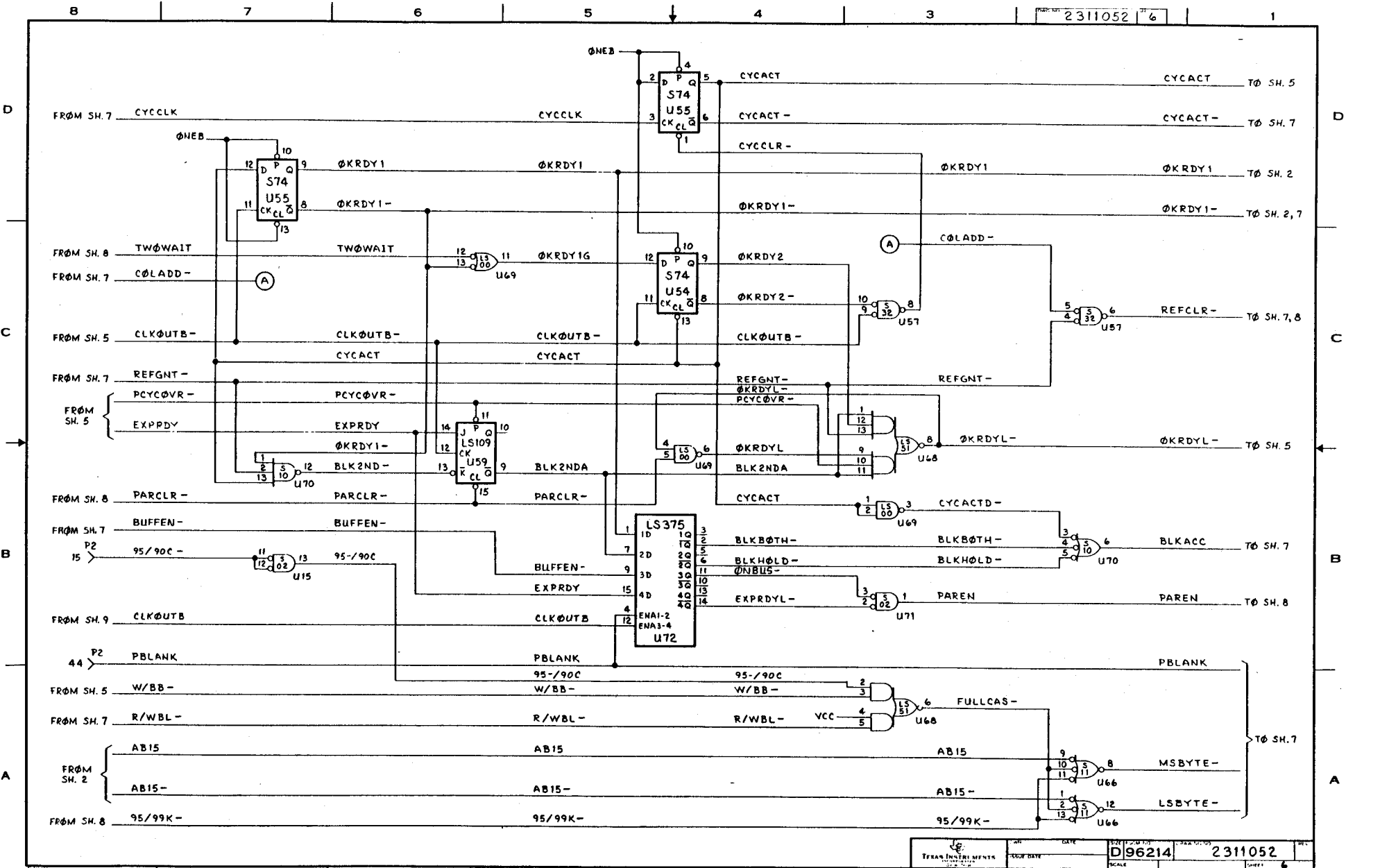


NOTE: ALL TMS4164'S ARE WIRED THE SAME EXCEPT FOR PINS 2 AND 14 AS SHOWN.

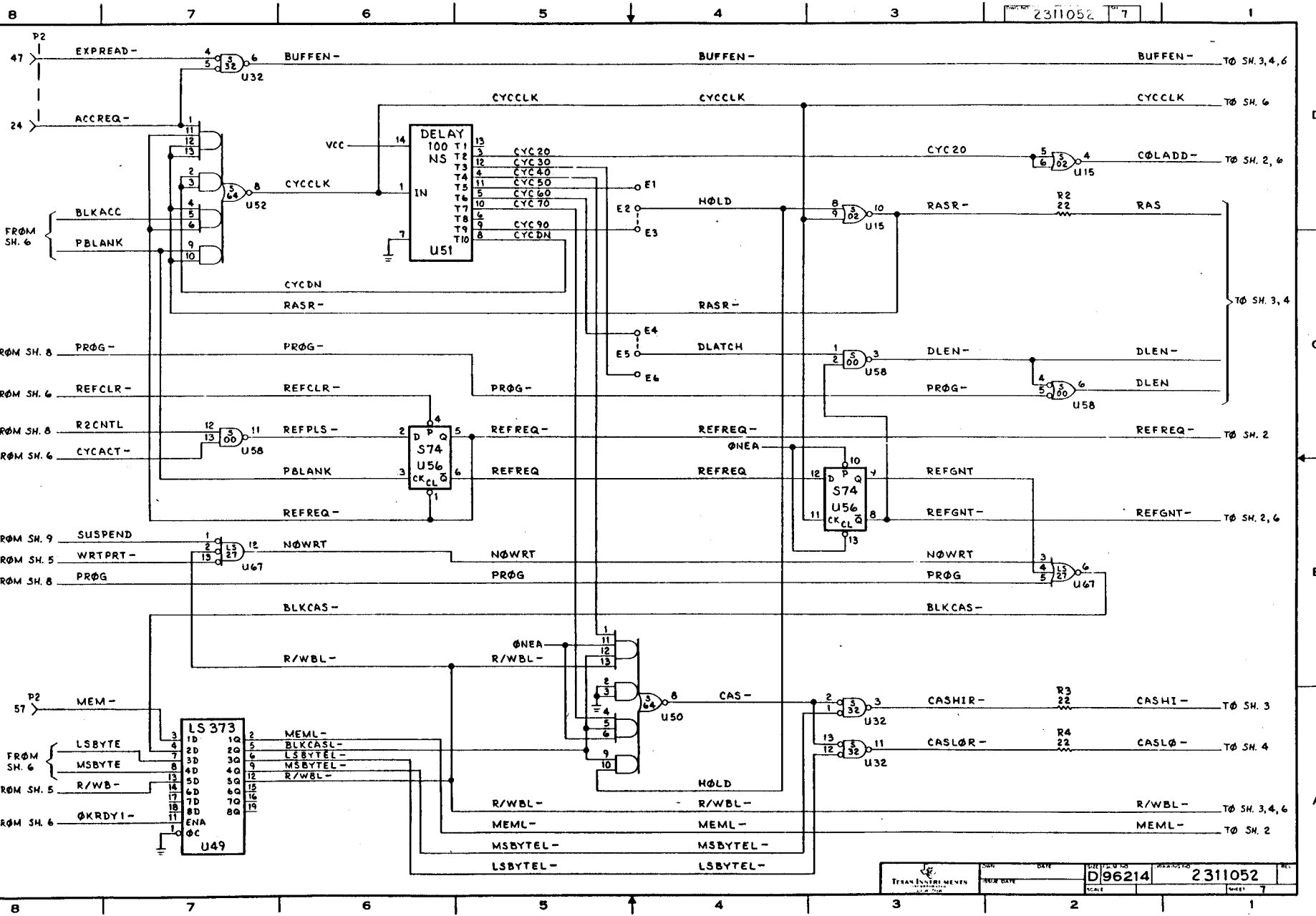


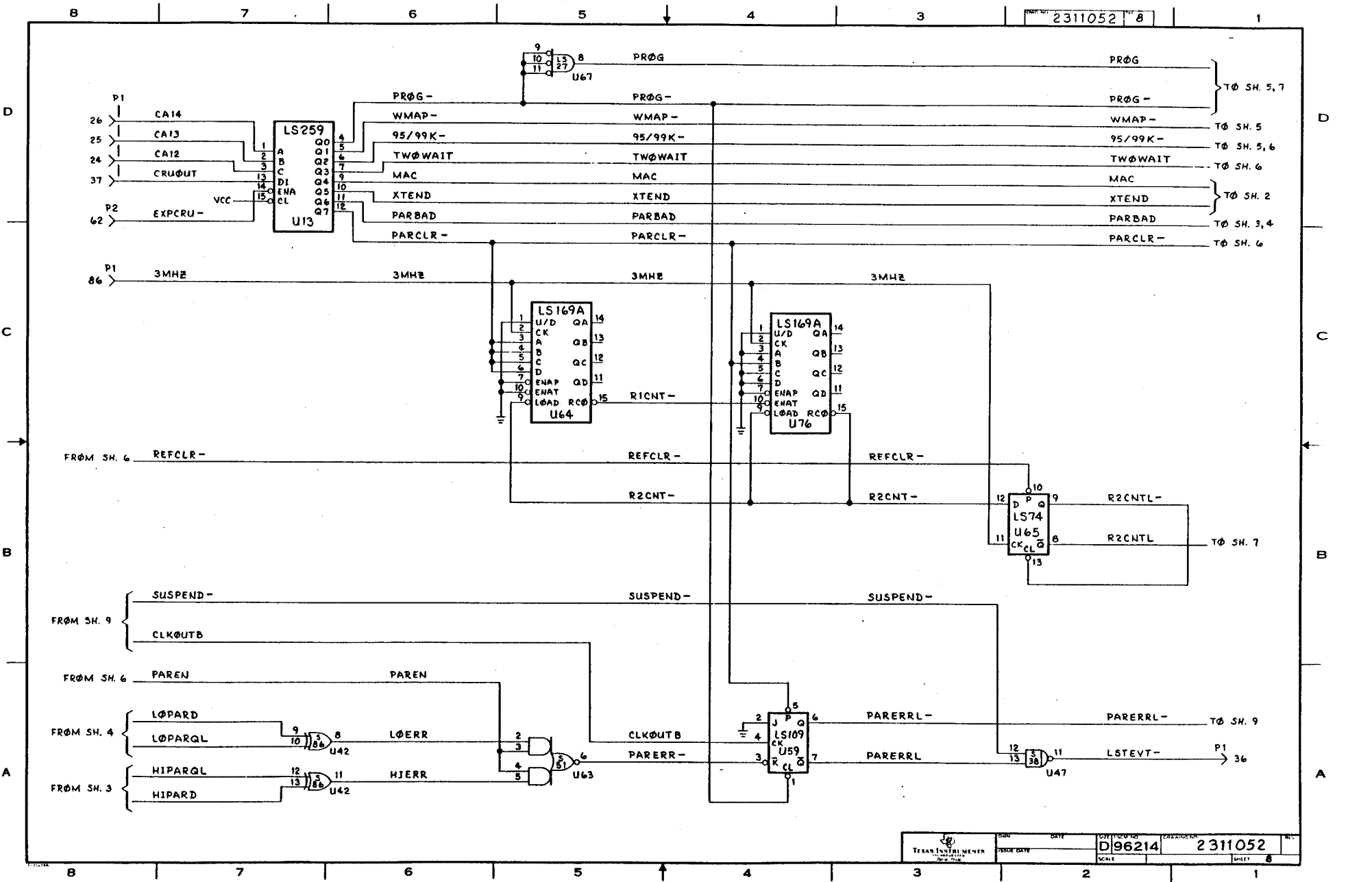
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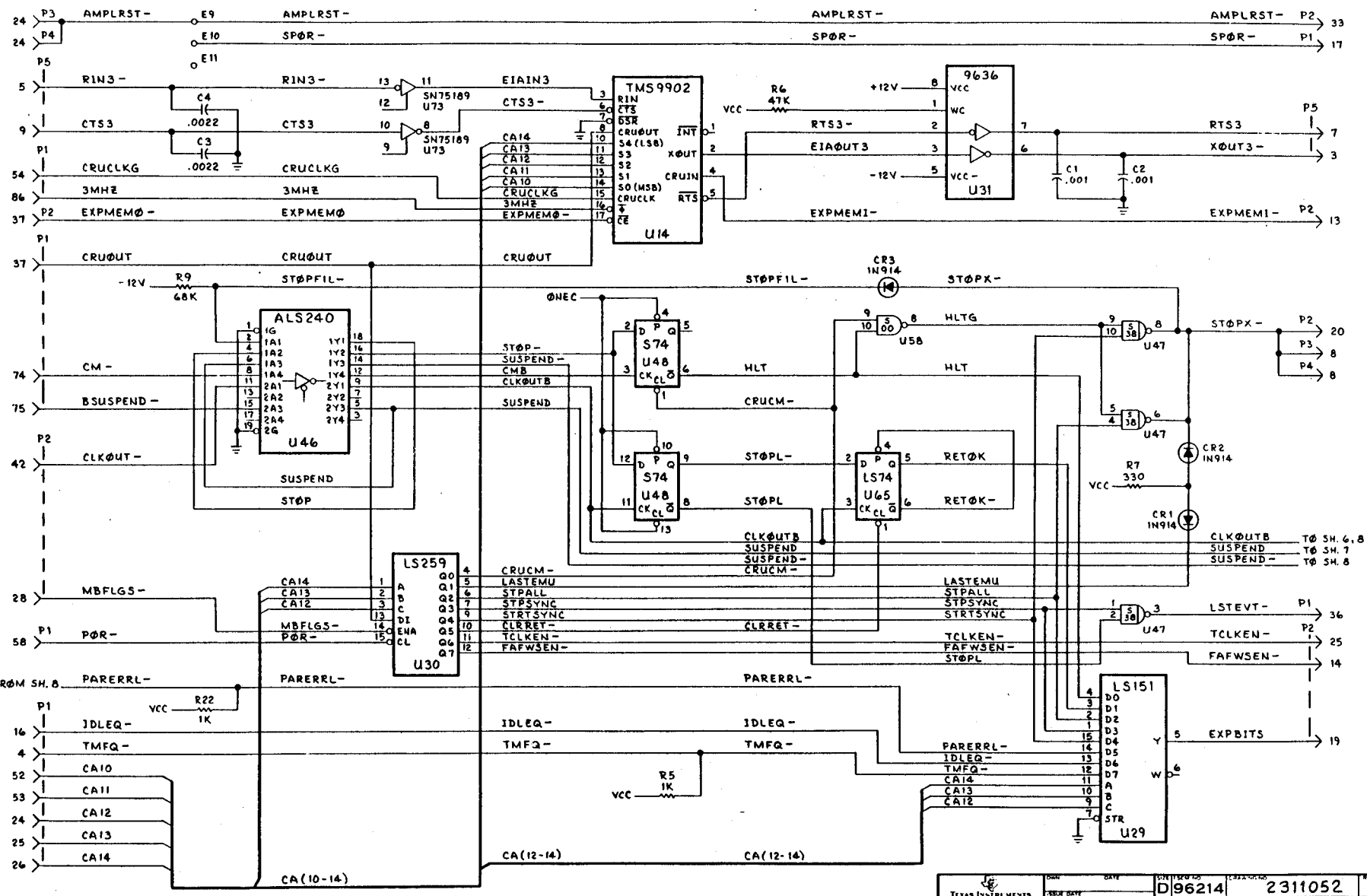


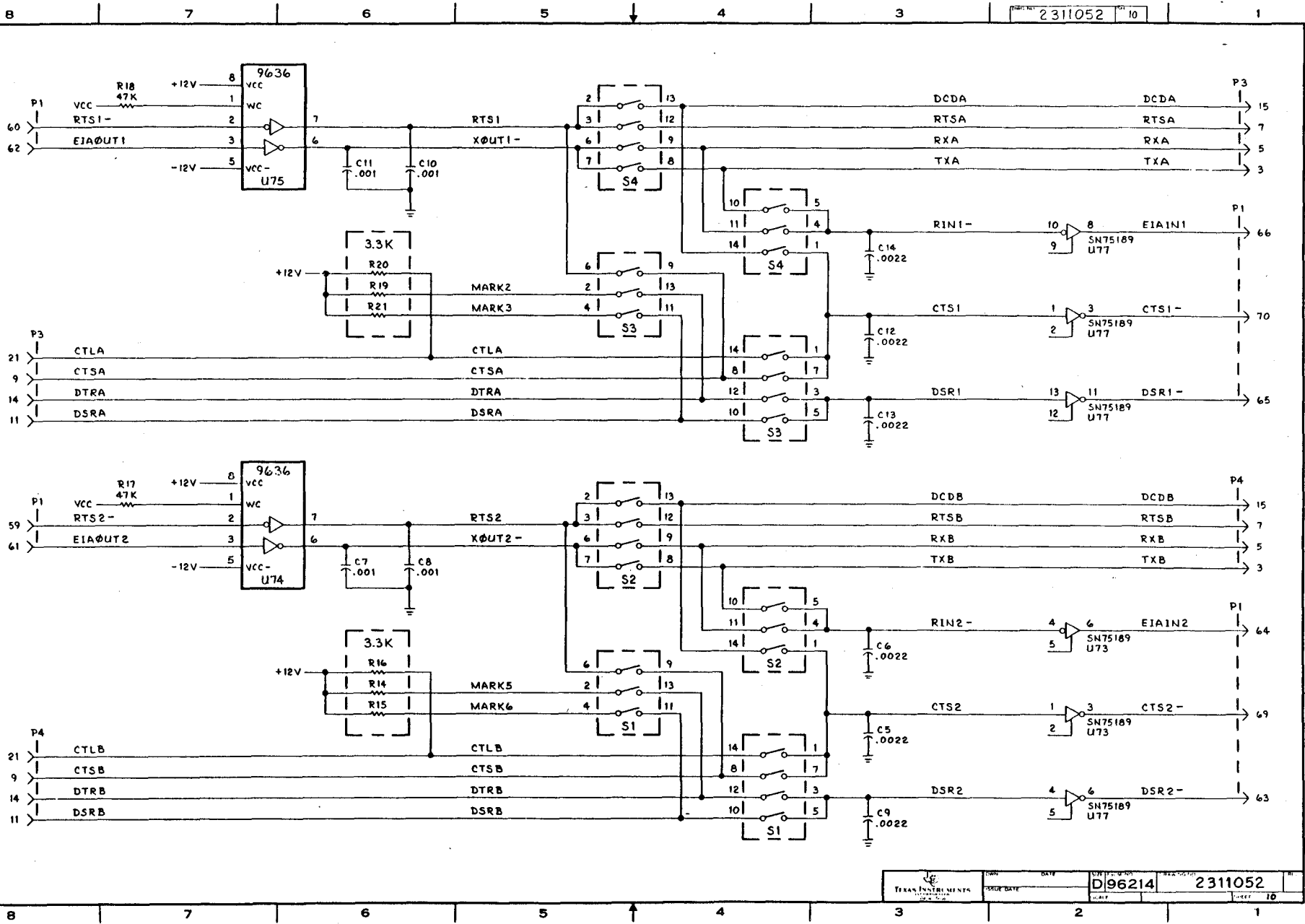


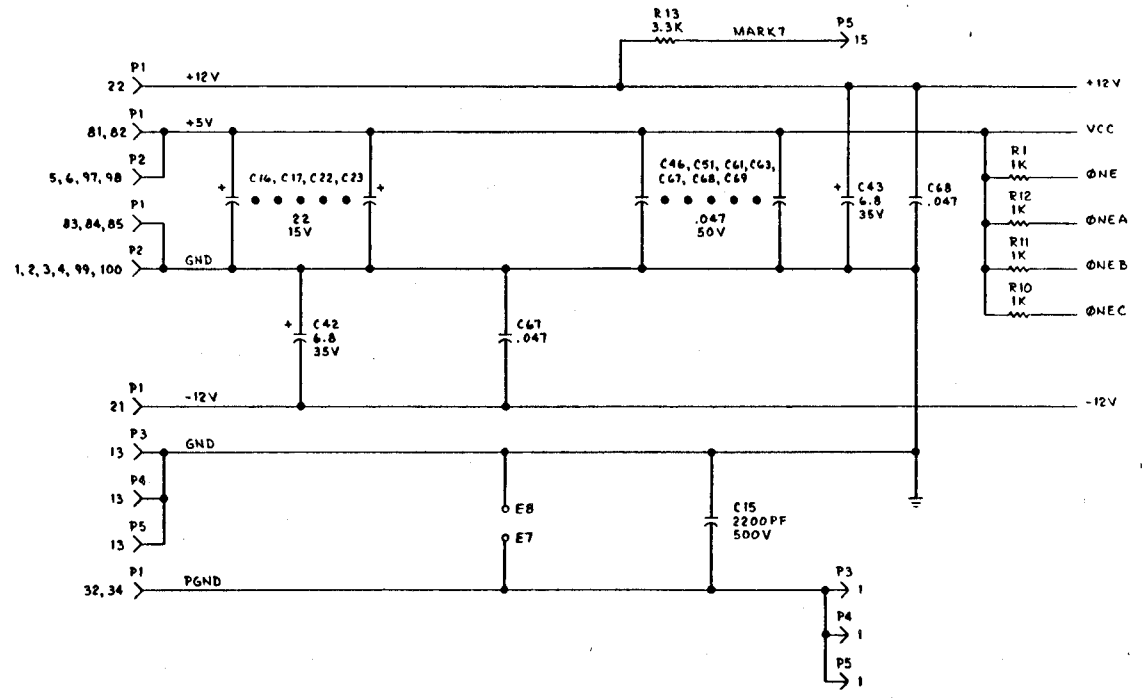








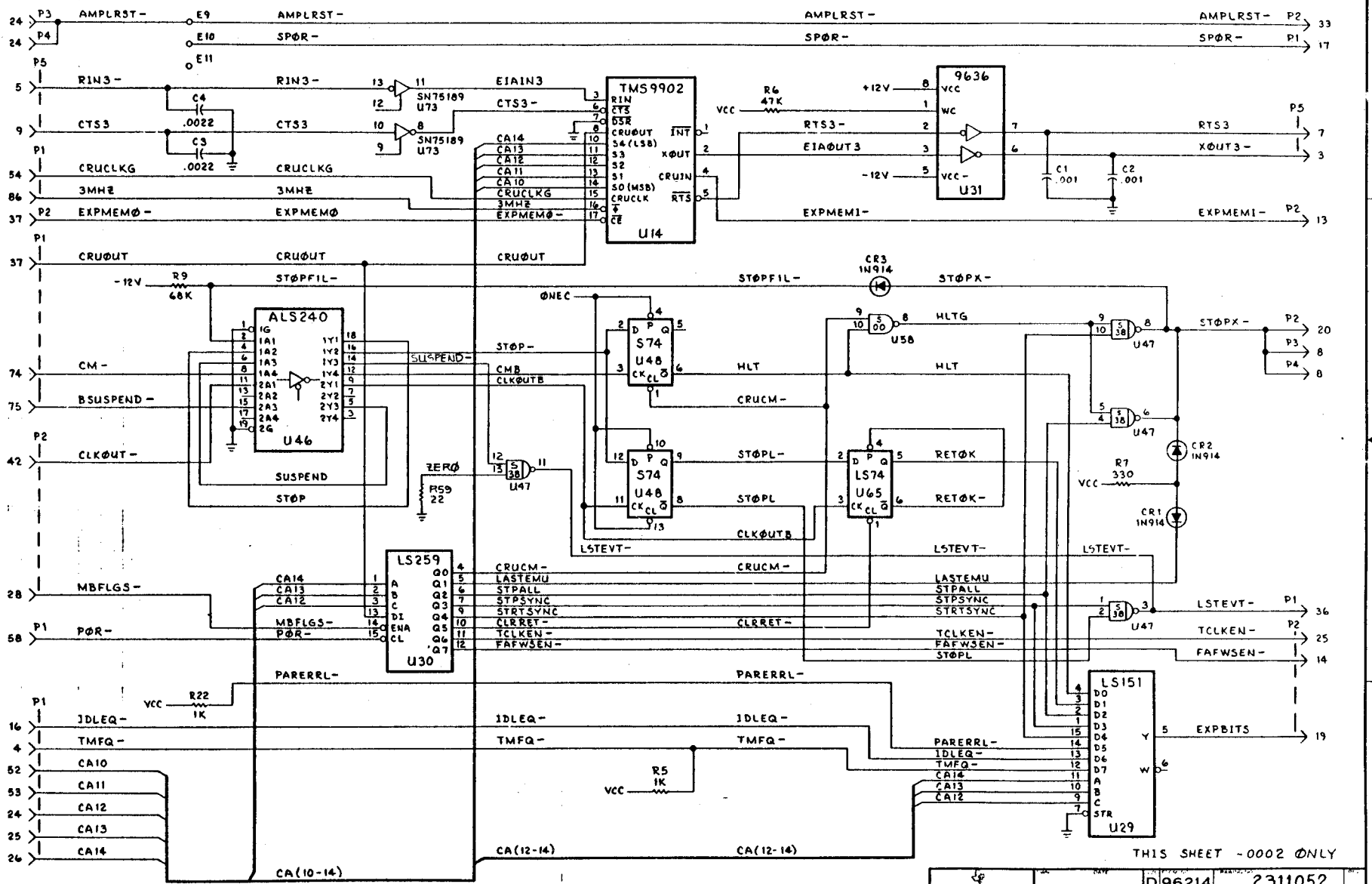




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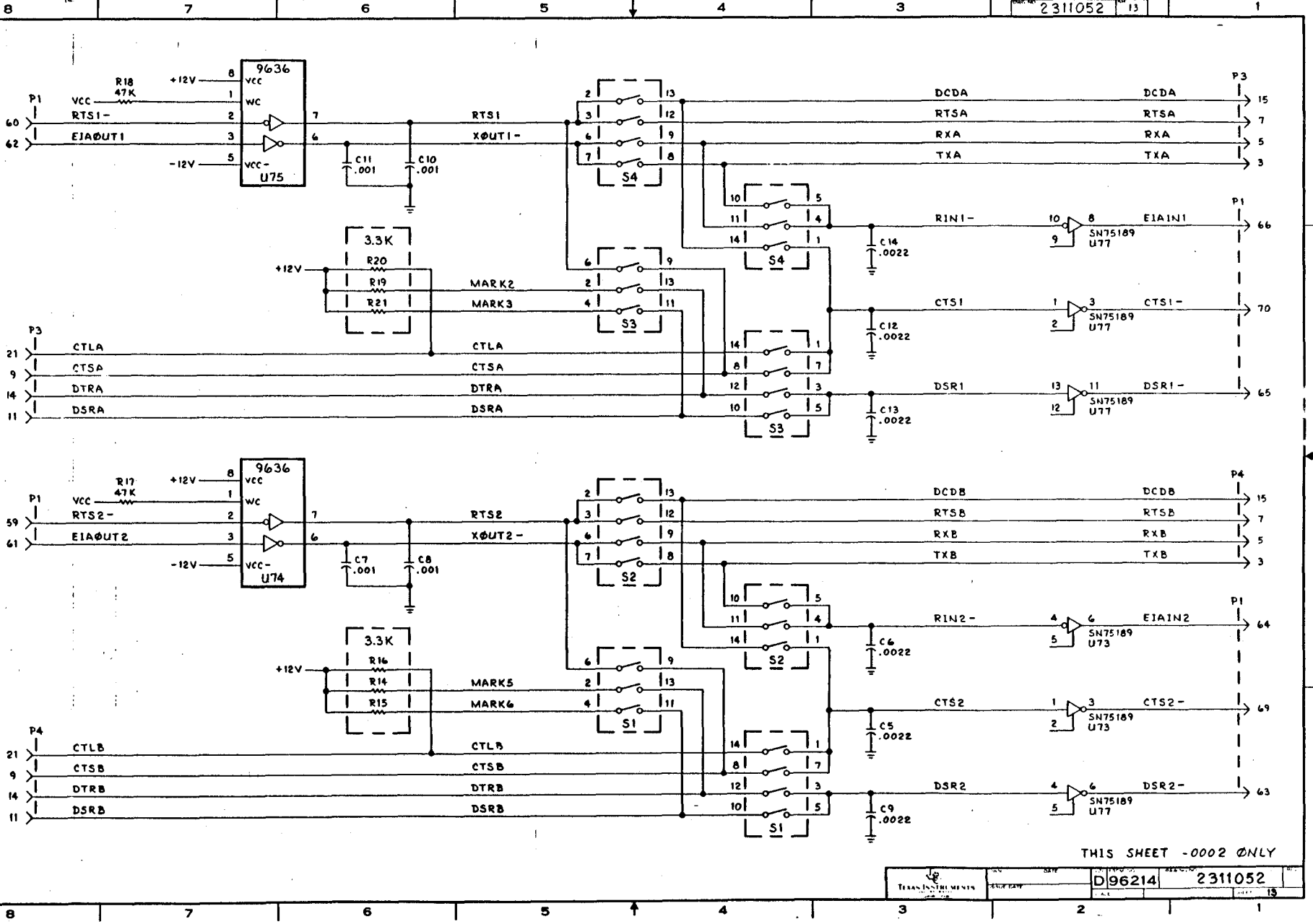




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